

Prepared	San Jing	Product Specifications AN7583	Ref No.	A-1
Checked	Kenneth Law		Total Page	11
Approved	H. J. Lin		Page No.	1

Structure	Silicon Monolithic Bipolar IC
Appearance	SIL-12 Pins Plastic Package (Power-type with Fin)
Application	Low Frequency Amplifier
Function	Dual 10W + Single 18W Audio Power Amplifier Built-in Muting Circuit Incorporating Protection Circuit



A Absolute Maximum Ratings					
No.	Item	Symbol	Ratings	Unit	Note
1	Storage Temperature	Tstg	-55 ~ +150	°C	1
2	Operating Ambient Temperature	Topr	-25 ~ +75	°C	1
3	Operating Ambient Pressure	Popr	1.013 x 10 ⁵ ± 0.61 x 10 ⁵	Pa	
4	Operating Constant Acceleration	Gopr	9,810	m/s ²	
5	Operating Shock	Sopr	4,900	m/s ²	
6	Supply Voltage	Vcc	35.0	V	
7	Supply Supply Current	Icc	8.0	A	
8	Power Dissipation	PD	37.5	W	2

Power Supply Voltage Range	Vcc	10.0 V ~ 32.0V
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Note) 1. Except these items, all other measurements are taken at Ta = 25°C.
2. Ta = 75°C with infinite heatsink.



Eff. Date	Eff. Date	Eff. Date	Eff. Date
02-JUN-2003			

Prepared	Sun Jing	Product Specifications AN7583	Ref No.	B - 1
Checked	Kenneth Law		Total Page	11
Approved	Higuchi		Page No.	2

No.	Item	Symbol	Condition	Limit			Unit	Note
				Min	Typ	Max		
B Electrical Characteristics (Unless otherwise specified, the ambient temperature is $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$, $f=1\text{kHz}$, $R_L=8\Omega$ and $V_{CC}=26\text{V}$.)								
1	Quiescent Current	ICQ	Vin=0mV	-	100	200	mA	
2	Output End Noise Voltage	Vno	No Input Rg = 10kΩ	-	0.22	0.4	mV	1
3	Voltage Gain	Gv	Vin = 57mV	32	34	36	dB	
4	Total Harmonic Distortion	THD	Vin = 57mV	-	0.2	0.4	%	
5	Maximum Output Power Channel 1 or 2	Po1	THD = 10%	8	10	-	W	
6	Maximum Output Power Channel 3	Po2	RL = 4Ω THD = 10%	15	18	-	W	
7	Ripple Rejection Ratio	RR	Vr=1Vrms, fr=120Hz Rg=10kΩ	45	53	-	dB	1
8	Channel Balance	CB	Vin = 57mV	-1.0	0	1.0	dB	
9	Muting Ratio	MR	Vin = 57mV	70	80	-	dB	
10	Muting Control Voltage	Vmute	Vin = 57mV MR > 70dB	3.0	-	-	V	
11	Channel Crosstalk	CT	Vin = 57mV Rg = 10kΩ	50	60	-	dB	

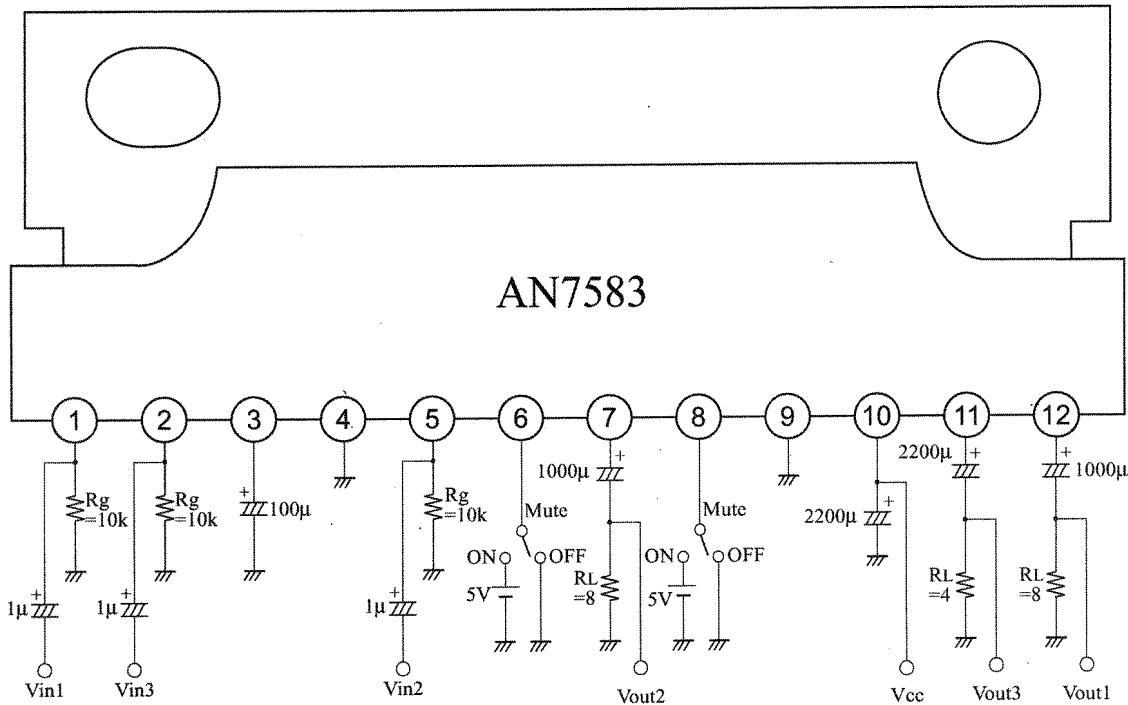
Note 1) For this measurement, use the 20Hz~20kHz (12dB/OCT) filter.

Eff. Date	Eff. Date	Eff. Date	Eff. Date	
02-JUN-2003				

Prepared	Sun Jing	Product Specifications AN7583	Ref No.	C-1
Checked	Kenneth Law		Total Page	11
Approved	Higuchi		Page No.	3

Description of Test Circuits and Test Methods

Test Circuit



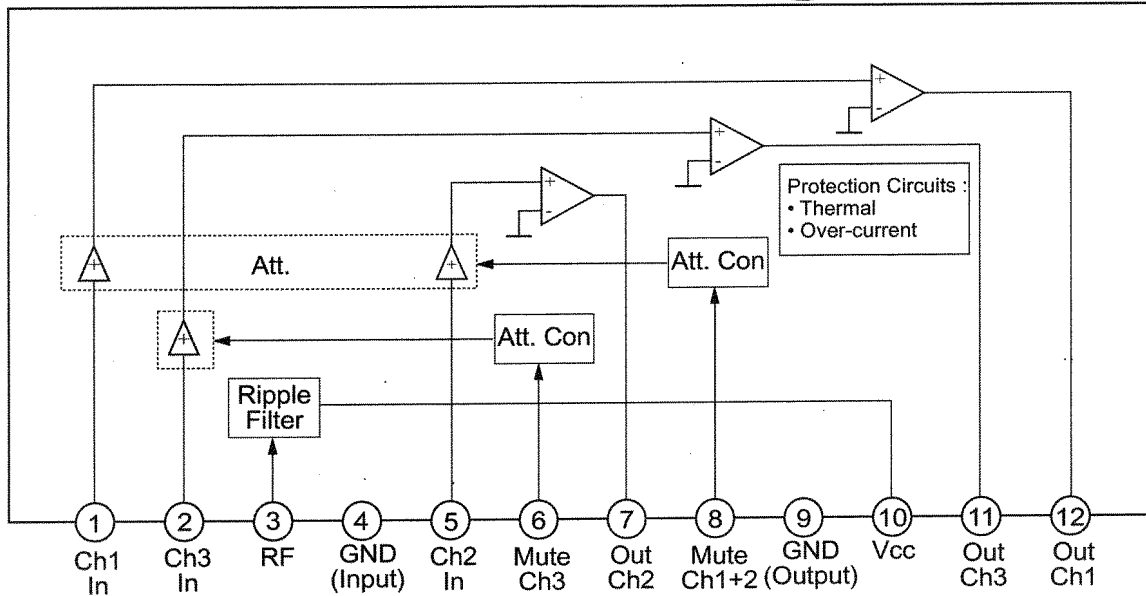
Note: MUTE 'OFF', connect to 0V.

Eff. Date	Eff. Date	Eff. Date	Eff. Date
21-MAY-2003			

Prepared	Sun Jing	Product Specifications AN7583	Ref No.	D-1
Checked	Kenneth Law		Total Page	11
Approved	Ziguli		Page No.	4



Circuit Function Block Diagram



Pin Descriptions

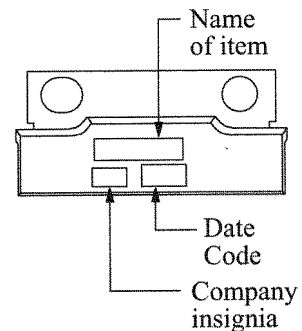
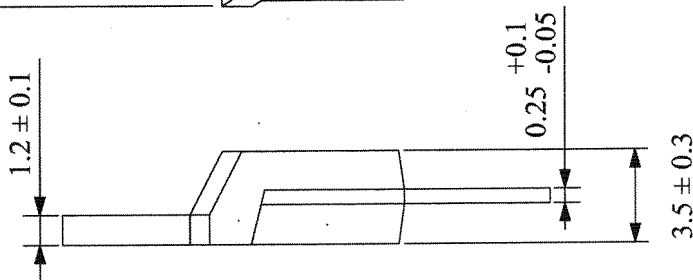
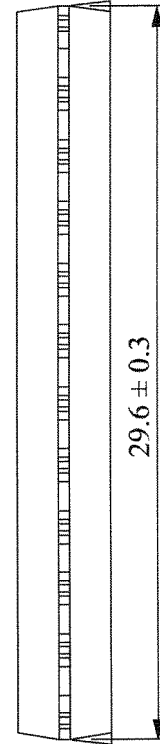
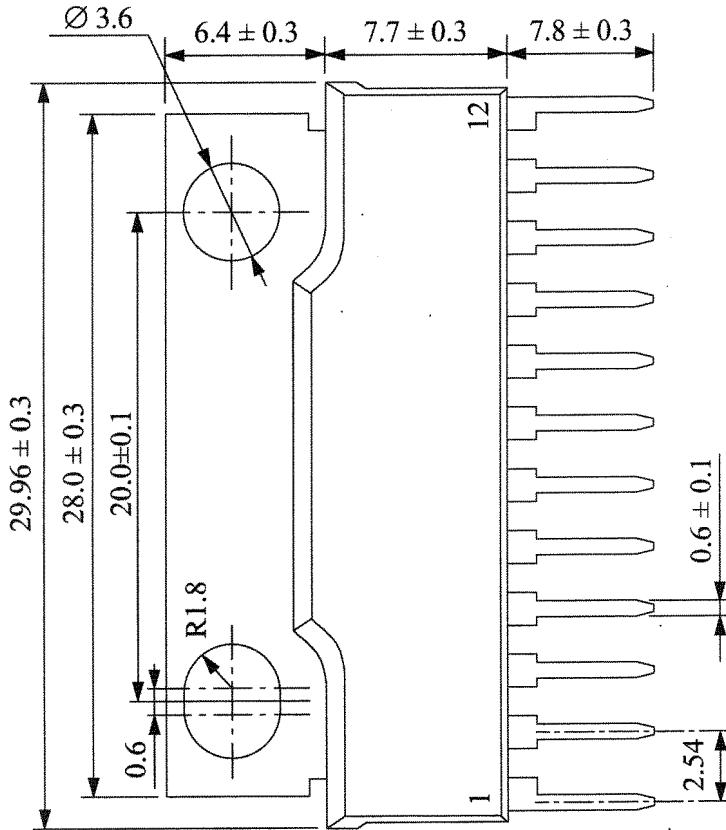
Pin No.	Pin Name	Pin No.	Pin Name
1	Channel 1 Input	7	Channel 2 Output
2	Channel 3 Input	8	Channel 1 & 2 Mute
3	Ripple Filter	9	Output GND
4	Input GND	10	Vcc
5	Channel 2 Input	11	Channel 3 Output
6	Channel 3 Mute	12	Channel 1 Output

Eff. Date	Eff. Date	Eff. Date	Eff. Date
02-JUN-2003			

Prepared	Sun Jing	Product Specifications AN7583	Ref No.	E
Checked	Kenneth Law		Total Page	11
Approved	Higuli		Page No.	5

Package Name	FP-12S
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Unit : mm



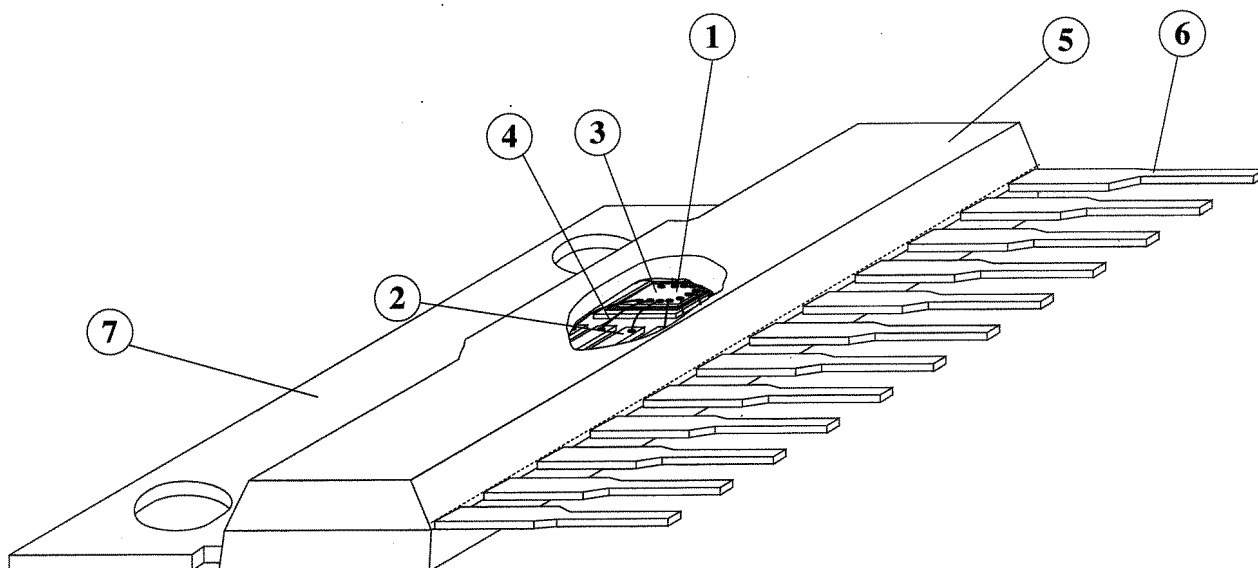
Eff. Date	Eff. Date	Eff. Date	Eff. Date
02-JUN-2003			

Prepared	Sun Jing	Product Specifications AN7583	Ref No.	F
Checked	Kenneth Law		Total Page	11
Approved	H. Zuli		Page No.	6

(Structure Description)

Chip surface passivation	SiN,	PSG,	Others ()	①
Lead frame material	Fe group,	Cu group,	Others ()	②, ⑥
Inner lead surface process	Ag plating,	Au plating,	Others ()	②
Outer lead surface process	Solder plating,	Solder dip,	Others ()	⑥
Chip mounting method	Ag paste,	Au-Si alloy,	Solder, Others ()	③
Wire bonding method	Thermalsonic bonding,		Others ()	④
Wire material	Au,	Others ()		④
Mold material	Epoxy,	Multiplunger mold,	Others ()	⑤
Molding method	Transfer mold,		Others ()	⑤
Heat Fin Material	Fe group,	Cu group,	Others ()	⑦

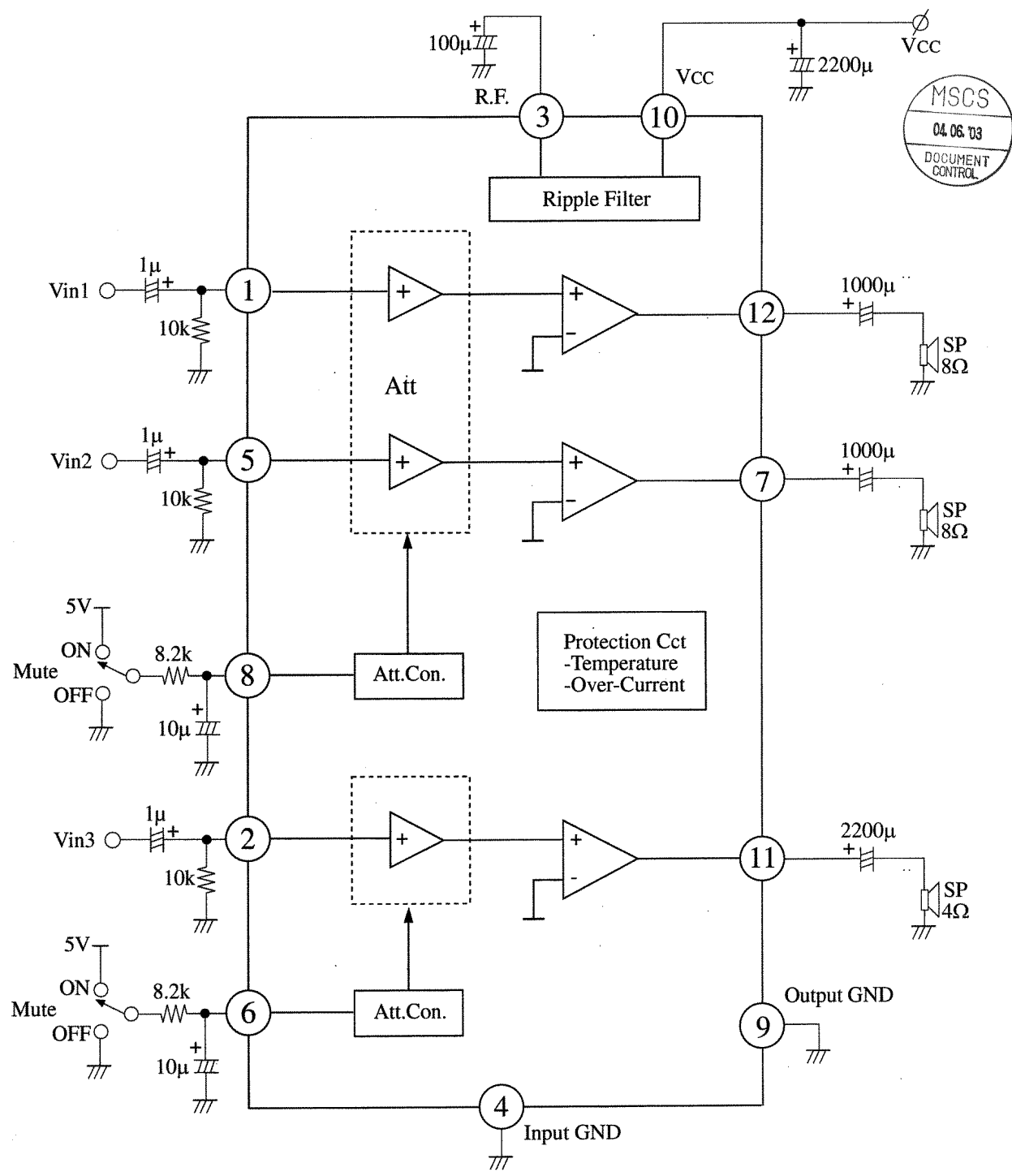
Package FP-12S



Eff. Date	Eff. Date	Eff. Date	Eff. Date
02-JUN-2003			

Prepared	Sun Jing	Product Specifications (Technical Data) AN7583	Ref No.	G-1
Checked	Kenneth Law		Total Page	11
Approved	Higulin		Page No.	7

Application Circuit



Mute 'OFF'	0V
Mute 'ON'	5V

Eff. Date	Eff. Date	Eff. Date	Eff. Date
02-JUN-2003			

Prepared	Sun Jing	Product Specifications (Technical Data) AN7583	Ref No.	G-2
Checked	Kenneth Law		Total Page	11
Approved	Higulin		Page No.	8

Pin No.	Function	Adjacent Circuitry	Description	DC Bias (V)
1 2 5	Input		This is the amplifier input pin. 	0V
3	Ripple Filter		This is the pin to connect the positive terminal of a ripple filter capacitor.	$V_{cc} - 1.5V_{BE}$
4	Input GND		Input ground pin.	0V

Eff. Date	Eff. Date	Eff. Date	Eff. Date
21-MAY-2003			

Prepared	Sun Jing	Product Specifications (Technical Data) AN7583	Ref No.	G-2
Checked	Weneth Law		Total Page	11
Approved	Higulin		Page No.	9

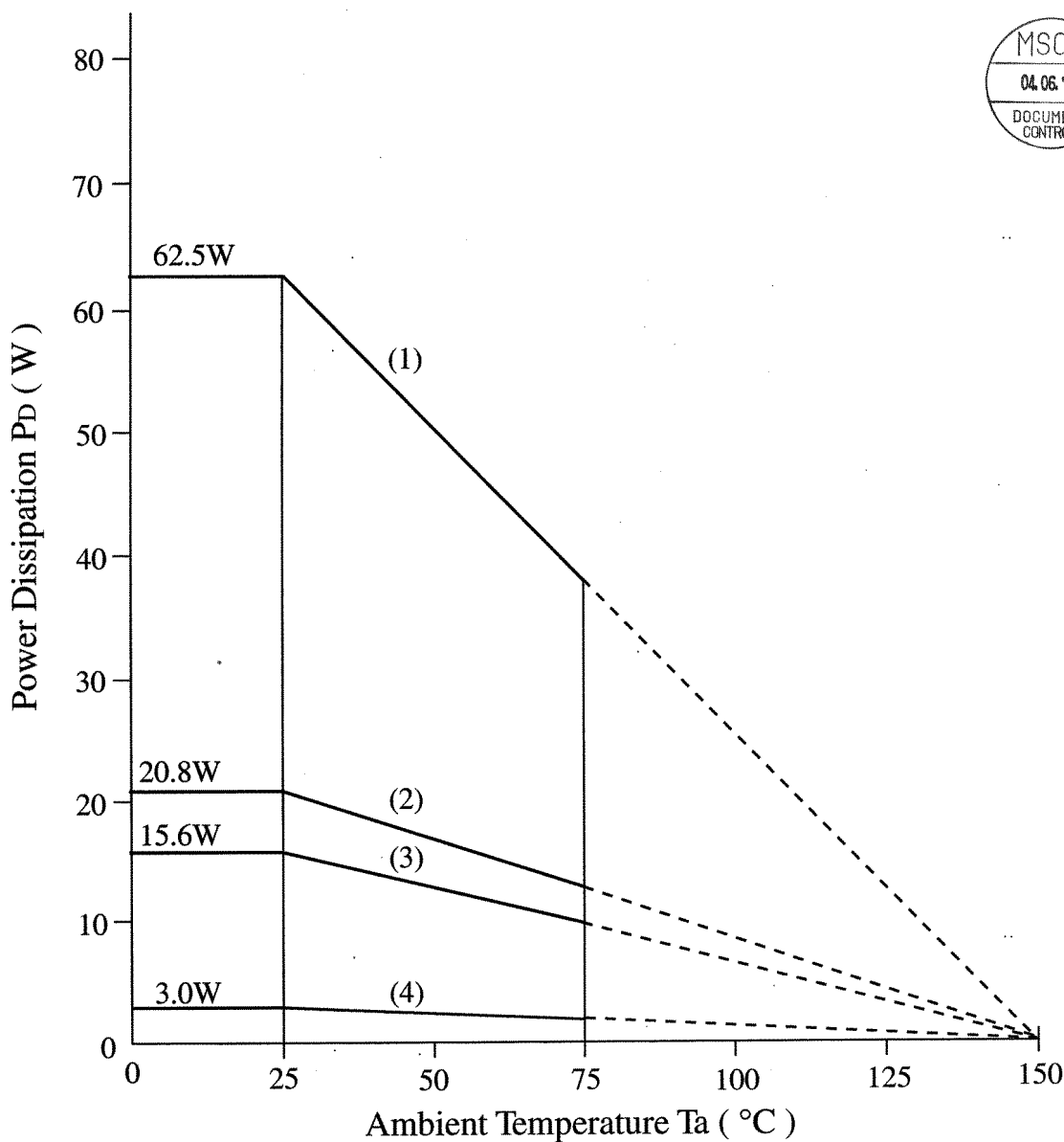
Pin No.	Function	Adjacent Circuitry	Description	DC Bias (V)
6, 8	Ch3 Mute Ch1 & 2 Mute		Mute input pin. Mute 'On' = 5V Mute 'Off' = 0V <div style="float: right; border: 1px solid black; border-radius: 50%; padding: 5px; text-align: center;"> MSCS 04.06.03 DOCUMENT CONTROL </div>	
7, 11, 12	Output		Output pin	Vcc/2
9	Output GND		Output ground.	0V
10	Vcc		This is the power supply pin.	Typ: 26V

Eff. Date	Eff. Date	Eff. Date	Eff. Date
21-MAY-2003			

Prepared	Sun Jing	Product Specifications (Technical Data) AN7583	Ref No.	G-3
Checked	Kenneth Law		Total Page	11
Approved	Higuli		Page No.	10

Pd - Ta Curves

- (1) $T_c = T_a$, 62.5W ($\theta_{j-c} = 2^\circ\text{C/W}$)
- (2) 20.83W ($\theta_f = 4.0^\circ\text{C/W}$)
With a 100cm² x 3mm Al heat sink (black colour coated)
or a 200cm² x 2mm Al heat sink (not lacquered)
- (3) 15.63W ($\theta_f = 6.0^\circ\text{C/W}$)
With a 100cm² x 2mm Al heat sink (not lacquered)
- (4) 3.0W at $T_a = 25^\circ\text{C}$ ($\theta_{j-a} = 42^\circ\text{C/W}$)
Without heat sink



Eff. Date	Eff. Date	Eff. Date	Eff. Date
02-JUN-2003			

Prepared	Sun Jing	Product Specifications AN7583	Ref No.	H
Checked	Kenneth Law		Total Page	11
Approved	Higuli		Page No.	11

Application's Precautions



- (1) External heatsink is needed when used. External heatsink should be fixed to the chassis.
- (2) Fin of the IC can be connected to GND.
- (3) Please prevent "Adjacent Pin Short", "Pin to Ground Short", "Pin to Vcc Short", "Pin Shift", "Reverse Insertion" and "Load Short above Vcc = 26V"
- (4) When operating beyond Vcc = 30V, the mute pin should be in the ON state before doing Vcc ON/OFF.
- (5) The temperature protection circuit will operate at Tj around 150°C. However, if temperature decrease, the protection circuit will automatically be deactivated and resume normal operation.
- (6) For the condition of chip junction temperature below the minimum thermal shutdown temperature, under continuous operation, this will not cause damage to the IC for the recommended application. The minimum thermal shutdown temperature of this IC is 140°C. This value is provided as a design reference and it is not guaranteed by testing.

Eff. Date	Eff. Date	Eff. Date	Eff. Date
21-MAY-2003			